

Cu/ETCH ME-1029 Low Foaming Spray Micro-Etch

Product Description

Cu/ETCH ME-1029 (ME-1029) is a low foaming, sprayable micro-etch. ME-1029 will clean and deoxidize bare copper printed circuit boards.

Performance Features

- Low Foaming
- Formulated for Spray Applications
- Cleans and Deoxidizes Bare Copper

Physical Specifications

Appearance	Amber Liquid
Odor	Slightly Acidic
Specific Gravity	1.14
Flash Point	Non-Flammable
Rinseability	Complete

Equipment Requirements

Containers: Polyethylene And Polypropylene

Heaters: Quartz Or Teflon

Product Make-Up / Operating Parameters

Make Up	20% To Full Strength
Temperature / Time	Operate Between 80 - 120°F For 1 – 2 Minutes.
Etch Rate	10 – 30 Millionths Per Minute.

Safety and Handling

Read and understand the MSDS before use.

Waste Treatment

Individual users should verify the nature of spent solutions to assure compliance with local, state, and federal regulations. Contact Seacole for specific details and/or further waste treatment recommendations.

Ordering Information

ME-1029 is available in 5-gallon pails and 55-gallon drums.

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